

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yaojian Lin</td> <td>01/04/2012</td> </tr> <tr> <td>Kang Chen</td> <td>01/04/2012</td> </tr> <tr> <td>Yu Gu</td> <td>01/04/2012</td> </tr> <tr> <td>Chee Siang Ong</td> <td>01/04/2012</td> </tr> <tr> <td>Wei Meng</td> <td>01/04/2012</td> </tr> </tbody> </table>		Name	Execution Date	Yaojian Lin	01/04/2012	Kang Chen	01/04/2012	Yu Gu	01/04/2012	Chee Siang Ong	01/04/2012	Wei Meng	01/04/2012
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<table border="1"> <tr> <td>Name:</td> <td>STATS ChipPAC, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>10 Ang Mo Kio Street 65</td> </tr> <tr> <td>Internal Address:</td> <td>#05-17/20 Techpoint</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>569059</td> </tr> </table>		Name:	STATS ChipPAC, Ltd.	Street Address:	10 Ang Mo Kio Street 65	Internal Address:	#05-17/20 Techpoint	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	569059
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CORRESPONDENCE DATA													
<p>Fax Number: (480)499-9456 Phone: 480-499-9400 Email: main@plgaz.com <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: PATENT LAW GROUP Address Line 1: 605 W. Knox Road Address Line 2: Suite 104 Address Line 4: Tempe, ARIZONA 85284</p>													
ATTORNEY DOCKET NUMBER:	2515.0322												

OP \$40.00 13164015

NAME OF SUBMITTER:

Robert D. Atkins

Total Attachments: 5

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ASSIGNMENT AND AGREEMENT

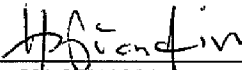
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of SINGAPORE, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD FOR FORMING SEMICONDUCTOR PACKAGE HAVING BUILD-UP INTERCONNECT STRUCTURE OVER SEMICONDUCTOR DIE WITH DIFFERENT CTE INSULATING LAYERS, which is described, illustrated, and claimed in U.S. Patent Application No. 13/164,015, filed June 20, 2011 and U.S. Provisional Application No. 61/435,215, filed January 21, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for YAOJIAN LIN

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

04 JAN 2012



DISCORA MERILO

5 YISHUN STREET 23

SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KANG CHEN of SINGAPORE, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD FOR FORMING SEMICONDUCTOR PACKAGE HAVING BUILD-UP INTERCONNECT STRUCTURE OVER SEMICONDUCTOR DIE WITH DIFFERENT CTE INSULATING LAYERS, which is described, illustrated, and claimed in U.S. Patent Application No. 13/164,015, filed June 20, 2011 and U.S. Provisional Application No. 61/435,215, filed January 21, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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chen kang
Signature for KANG CHEN

Witnessed on this date: 04 JAN 2012
Signature of Witness: [Signature]
Printed Name of Witness: DIOS CORDO MERILLO
Address of Witness: 5 YISHUN STREET 23
SINGAPORE 768442

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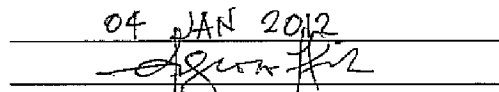
Signature for YU GU

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

04 JAN 2012

DIOSCORO MERILO
5 YISHUN STREET 23
SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

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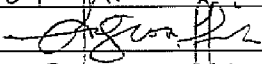
Signature for CHEE SIANG ONG

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

04 JAN 2012

DIOSCORO MERILLO
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Signature for WEI MENG

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

04 JAN. 2012
[Handwritten Signature]
DIOSCORO MERILO
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